

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (original): A flip chip mounting substrate which comprises an electronic circuit composed of a circuit line and plural mounting pads connected to both ends of the circuit line formed on one surface of a base sheet, wherein the plural mounting pads are faced each other and spaced a pad clearance gap apart, and one or more semiconductor mounting paste guide paths are formed in the mounting pads.
2. (original): The flip chip mounting substrate as claimed in claim 1, wherein a width of the semiconductor mounting paste guide path is in the range from 50 to 600  $\mu\text{m}$ .
3. (currently amended): The flip chip mounting substrate as claimed in claim 1, ~~or claim~~ 2 wherein a broad section for pressing out and spreading uniformly the semiconductor mounting paste to connecting to an IC ship is formed in a pat of the pad clearance gap.
4. (original): The flip chip mounting substrate as claimed in claim 3, wherein a thin film layer is formed in center section of the broad section.